

**600V N-Channel Enhancement Mode MOSFET**
**Features**

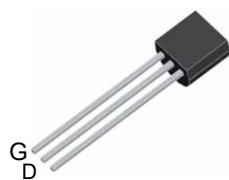
- Fast switching
- Low Gate Charge
- Improved dv/dt capability
- 100% avalanche tested
- Green Device Available

**Product Summary**

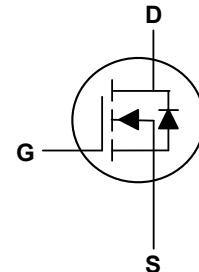

$V_{DS}$	600	V
$I_D$	1	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	11	$\Omega$

**Applications**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters



TO-92


**Absolute Maximum Ratings( $T_c=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>1</sup>	$I_D$	1	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	3	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	50	mJ
Total Power Dissipation <sup>4</sup>	$P_D$	3	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	110	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	4.17	°C/W

**600V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

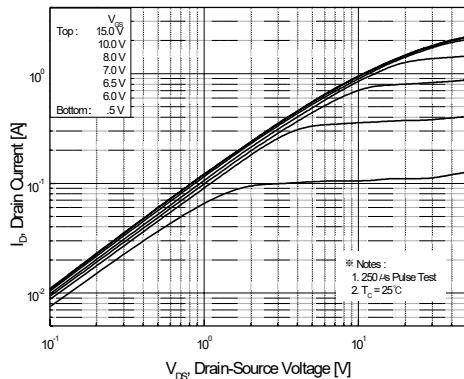
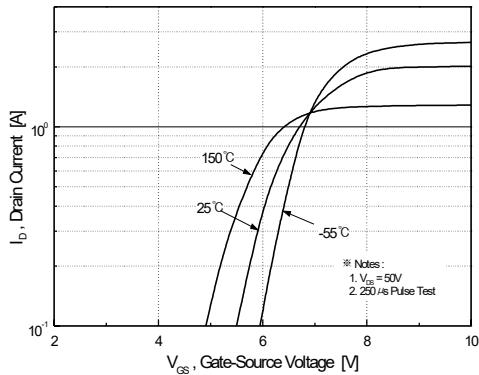
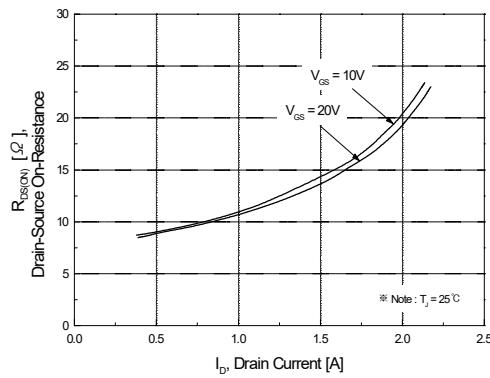
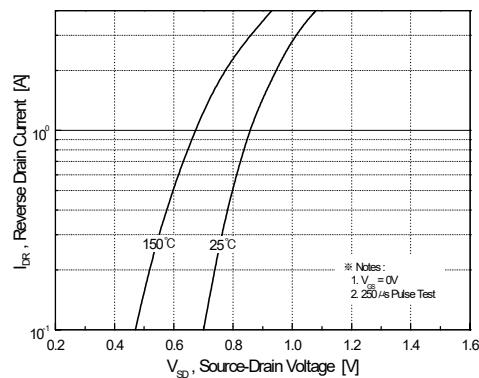
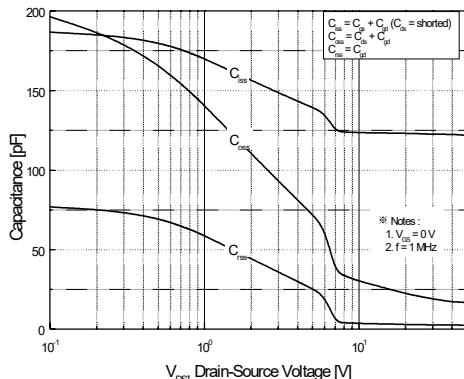
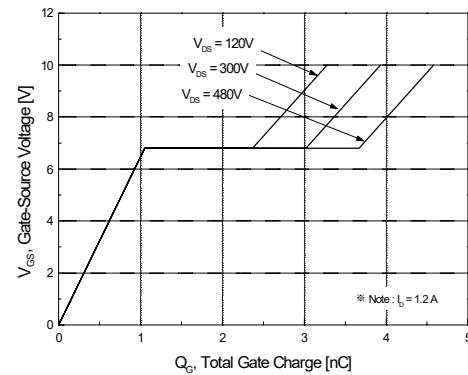
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	600	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=0.5\text{A}$	---	11	15	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	2.0	---	4.5	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=500\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\mu\text{A}$
Total Gate Charge	$Q_g$	$V_{\text{DD}}=480\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=1\text{A}$	---	5	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	1	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	2.6	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}$ , $R_G=25\Omega$ , $I_D=0.5\text{A}$	---	5	---	ns
Rise Time	$T_r$		---	25	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	7	---	
Fall Time	$T_f$		---	25	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	120	---	pF
Output Capacitance	$C_{\text{oss}}$		---	25	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	3	---	

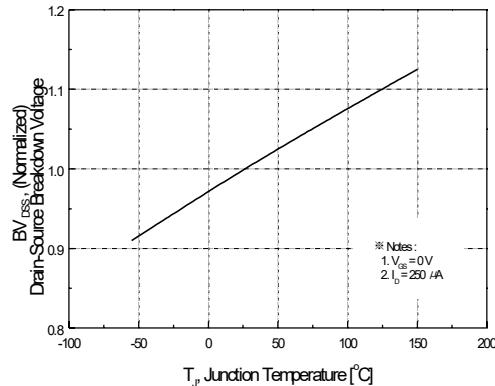
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=0.5\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_S=1\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	160	---	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		---	0.3	---	nC

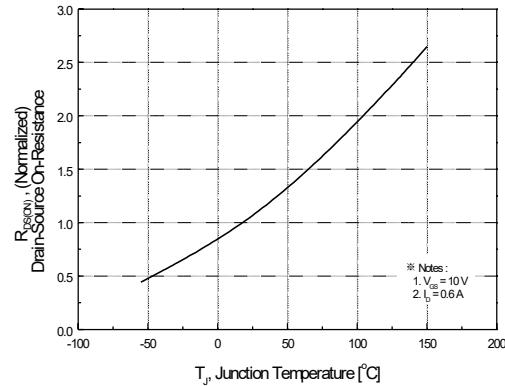
**Note:**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=10\text{mH}$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

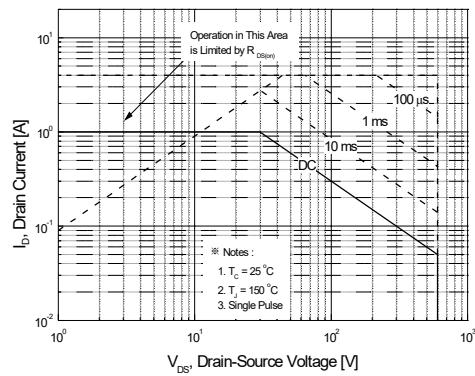
**600V N-Channel Enhancement Mode MOSFET**
**Typical Characteristics**

**Figure 1. On-Region Characteristics**

**Figure 2. Transfer Characteristics**

**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**

**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

**Figure 5. Capacitance Characteristics**

**Figure 6. Gate Charge Characteristics**

**600V N-Channel Enhancement Mode MOSFET**


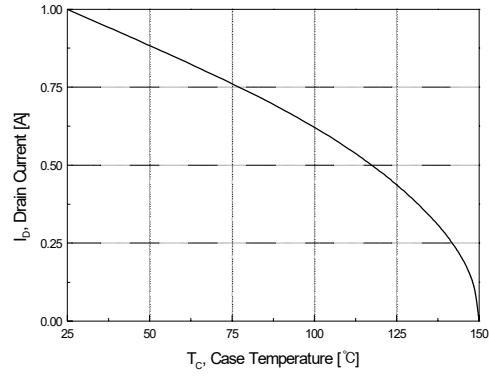
**Figure 7. Breakdown Voltage Variation  
vs. Temperature**



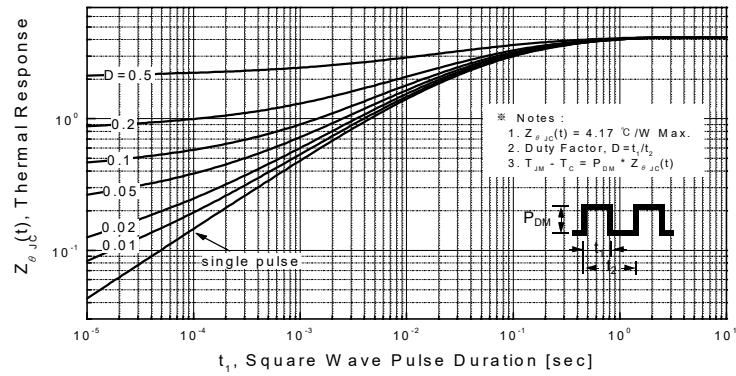
**Figure 8. On-Resistance Variation  
vs. Temperature**



**Figure 9. Maximum Safe Operating Area**

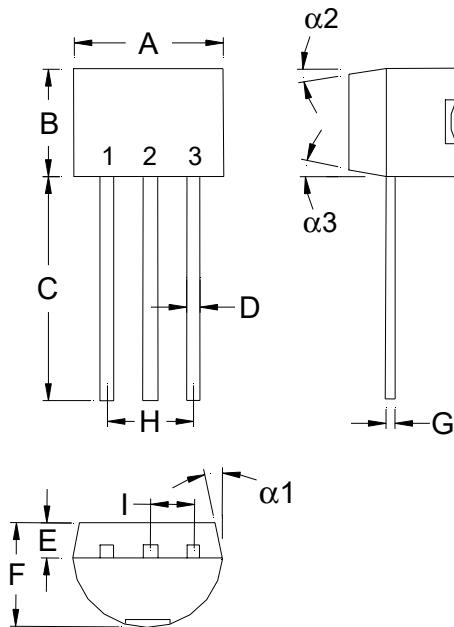


**Figure 10. Maximum Drain Current  
vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

### TO-92 Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°